15

20

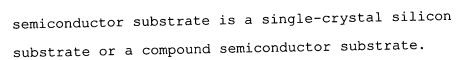
## WHAT IS CLAIMED IS:

 A method of manufacturing a display device, comprising:

the step of preparing a member having, on a separation layer, a semiconductor film having a first region with a switching element and a second region with a peripheral circuit;

the step of forming an image display portion on the first region; and

- the separation step of separating the first and second regions from the member together with the image display portion.
  - 2. The method according to claim 1, wherein the member is obtained by forming a porous layer on a surface of a semiconductor substrate, forming the semiconductor film on a surface of the porous layer, and then forming the first and second regions.
  - 3. The method according to claim 2, wherein the semiconductor film is formed on the surface of the porous layer after forming a protective film on inner walls of pores in the porous layer.
  - 4. The method according to claim 1, wherein the member is obtained by forming the first and second regions on a surface of a semiconductor substrate and implanting ions from the surface side to a
  - 25 implanting ions from the surface side to a predetermined depth to form the separation layer.
    - 5. The method according to claim 2, wherein the



- 6. The method according to claim 4, wherein the semiconductor substrate is a single-crystal silicon substrate or a compound semiconductor substrate.
- 7. The method according to claim 1, wherein the separation step is executed by injecting a fluid formed from a liquid or gas to or near a side surface of the separation layer.
- 10 8. The method according to claim 1, wherein the separation step is executed under a static pressure.
  - 9. The method according to claim 1, wherein the member is formed again using a remaining member which remains after the first and second regions are
- 15 separated from the member.
  - 10. A display device comprising:

a semiconductor film laid out on a separation surface and having a first region with a switching element and a second region with a peripheral circuit;

20 and

an image display portion laid out on the first region.